

32kHz Design for Low Power Applications



Version 1.1



Reducing Power Consumption for 32kHz Quartz Crystal Oscillator Circuit

Abstract

The intent of this investigation is to show the advantages of 32kHz crystals with reduced C_L and lower ESR over conventional 32kHz crystals with regard to power consumption, oscillation allowance, starting time and drive level.

The following draft confirms the advantage of the use of Geyer Electronic KX-327NHT with Load Capacitance of 7pF instead of 12,5pF.

Part number 12.87153	7pF	+/-20ppm	≤ 80k Ohm, 50k Ohm typ.
Part number 12.87148	7pF	+/-20ppm	≤ 50k Ohm, 35k Ohm typ.

- Considerably reduced Power Consumption

- Improved Start up Performance
- Faster Start up time
- Stable operation for lower drive level
- 1. Reducing Power Consumption in CMOS Oscillator Circuit
- 2. Relationship for C_L and Power Consumption in the Oscillator Circuit
- 3. Relationship of Negative Resistance (Oscillation Allowance) and CL
- 4. Relationship for Oscillator circuit current and R1
- 5. Another Advantage of Low-C_L (Oscillation Rising Time)
- 6. Another Advantage of Low-C_L (Drive Level)
- 7. Precision vs. Power Consumption

Annex: Circuit Matching Investigation

Annex: Data Sheets – Part number 12.87153, 12.87148 and 12.87150

1. Reducing Power Consumption in CMOS Oscillator Circuit

Current consumption of the crystal oscillator circuit depend on power supply voltage (Vdd), frequency, load capacitance, and R1 of the quartz crystal.

 Current consumption in the oscillator circuit 					
1. Charge and discharge current of CL	»	Low CL			
2. Flow-through current	»	Low R1			

 Low-CL and Low-R1 of the quartz crystal realizes reduction of power consumption in the oscillator circuit





2. Relationship for CL and Power Consumption in the Oscillator Circuit



Oscillator circuit current (Actual measurement)

$$Id = \frac{Vd}{1/(2\pi f)C_d} = (2\pi f)VdC_d$$

- Charge and discharge current for $C_L=7pF$ is 40% lower than for of 12,5pF.
- Actual measurement includes the flow-through current of the oscillation inverter. Therefore, when the flow-through current is controlled, the calculated values Approximate the actual reduction of the current consumption.





3. Relationship of Negative Resistance (Oscillation Allowance) and CL





$$-R_L = \frac{-g_m}{(2\pi f)^2 C_g C_d}$$

Reduction of g_m and V_{dd} lowers the IC's power consumption, which reduces the oscillation allowance. The Crystal's low – C_L offsets the reduction of oscillation allowance.



4. Relationship for Oscillator circuit current and R1



Oscillator circuit current (Actual measurement)

Oscillator amplitude on Cg (V)

- The current consumption of an oscillator circuit using 74HCU04 can decrease by Approximately 10% based on the quartz crystal motional resistance R1.
- Quartz crystal motional resistance R1 will be higher, the oscillator amplitude on Cg will be lower, and the flow-through current of oscillator will be higher.



5. Another Advantage of Low-CL (Oscillation Rising Time)

Low C_{L} makes a higher negative resistance. The oscillator rising time will be shorter if the C_{L} is lower.







6. Another Advantage of Low-C_L (Drive Level)

 $DL = I^2 x Re$

 $I = Vg/ (1/\omega C)$ Re = R1 x (1+Co/CL)²



Lower C_{L} reduces the quartz crystal excitation current and reduced the drive level. Excessive drive level makes the characteristics of the tuning fork quartz crystal unstable.



7. Precision vs. Power Consumption

While a crystal with a low load capacitance of $C_L = 7pF$ provides a design with low power consumption, a crystal with a higher load capacitance of $C_L = 12,5pF$ is more advantageous for applications requiring higher precision.

As you can see from the diagram, the slope at $C_L = 7pF$ is steeper than that at $C_L = 12,5pF$. This means that circuit tolerances have stronger influence on a 7pF-crystal than on a 12,5pF-crystal.



Therefore it is necessary to balance power consumption with precision.



Annex: Circuit Matching Investigation

Result of Matching Investigation

This is an example of our matching investigation for customers.

Our Crystal: KX-327NHT





Table 1. Constants

	А	В		
Key specifications	C∟	CL	Unit	Remarks
	12,5pF	7pF		
Vdd : V	3,3	3,3		
Capacitance at Input : Cg	20	6	pF	Optimal appagitance in response to C
Capacitance at Output : Cd	20	6	pF	

Table 2. Characteristic data

Item		CL	C∟	Unit	Remarks
		12,5pF	7pF		
Matching accurancy	∶⊿f/Fo	2,50	1,19	x10 ⁻⁶	Frequency offset at specified Vdd
Voltage Fluctuation	: +/-df/V	-	0,00	x10 ⁻⁶	Vdd +/-10% (Standard operating voltage range)
Drive Level	: DL	0,01	0,01	μW	DL=Ix2 Re < 1x10-6W, Re=R1 (1+Co/ C _L)2
Negative Resistance	: I –RL I	-665	-1063	kOhm	5 times larger than R1MAX Judgemental standard
Oscillation Allowance	: M	9,5	15,2	Times	of oscillation stability
Oscillation Starting Volt	age	-	1,43	V	
Oscillation Stopping Vo	ltage	-	1,36	V	

11/2015









Quartz Crystal

SMD-version

model	KX–327NHT
frequency	32,768 kHz
operating temperature	-40° ~ +85°C
frequency tolerance at +25°C	± 20 ppm
temperature tolerance (parabolic coefficient) at -40° ~ +85°C	-0,035 ppm/°C ² typ.
turnover temperature	+25°C ± 5°C
storage temperature range	-55°C ~ +125°C
load capacitance C _L	7pF
motional capacitance (C1)	0,0036 pF, typ.
series resonance R ₁ max.	80k Ohm
aging at +25°C (first year) max.	± 3 ppm max.
shunt capacitance C _o	1,3 pF (1,0 pF typ.)
drive level in μW max.	0,1 typ. (1,0 μW max.)
quality factor (Q)	20000 min.
reflow soldering condition	10 seconds at +260°C max. (2 times max.)
contents of reel	3000 pcs.
part no.	12.87153

Dimensions (mm):



Reflow soldering condition:





Tape specification:















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load capacitance C _L	7 pF
motional capacitance (C1)	0,0036 pF, typ.
series resonance R ₁ max.	50k Ohm
aging at +25°C (first year) max.	± 3 ppm
shunt capacitance C _O	1,3 pF (1,0 pF typ.)
drive level in μW max.	0,1 typ. (1,0 μW max.)
quality factor (Q)	20000 min.
reflow soldering condition	10 seconds at +260°C max. (2 times max.)
contents of reel	3000 pcs.
part no.	12.87148
Remarks:	
Recommended for ST Microelectron	nics STM 32 STM 8

Recommended for Intel 8-series, PCH-LP, C220 series



Suggested soldering pad:



Reflow soldering condition:



Tape specification:



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turnover temperature	+25°C ± 5°C
storage temperature range	-55°C ~ +125°C
load capacitance CL	12,5 pF
motional capacitance (C1)	0,0036 pF, typ.
series resonance R ₁ max.	80k Ohm
aging at +25°C (first year) max.	± 3 ppm
shunt capacitance Co	1,3 pF (1,0 pF typ.)
drive level in μW max.	0,1 typ. (1,0 μW max.)
quality factor (Q)	20000 min.
reflow soldering condition	10 seconds at +260°C max. (2 times max.)
contents of reel	3000 pcs.
part no.	12.87150







Suggested soldering pad:



Reflow soldering condition:



Tape specification:

